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Qualification and Performance Specification for Rigid Printed Boards

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Qualification and Performance Specification for Rigid Printed Boards

Developed by the Rigid Printed Board Performance Specifications Task Group (D-33a) of the Rigid Printed Board Committee (D-30) of IPC

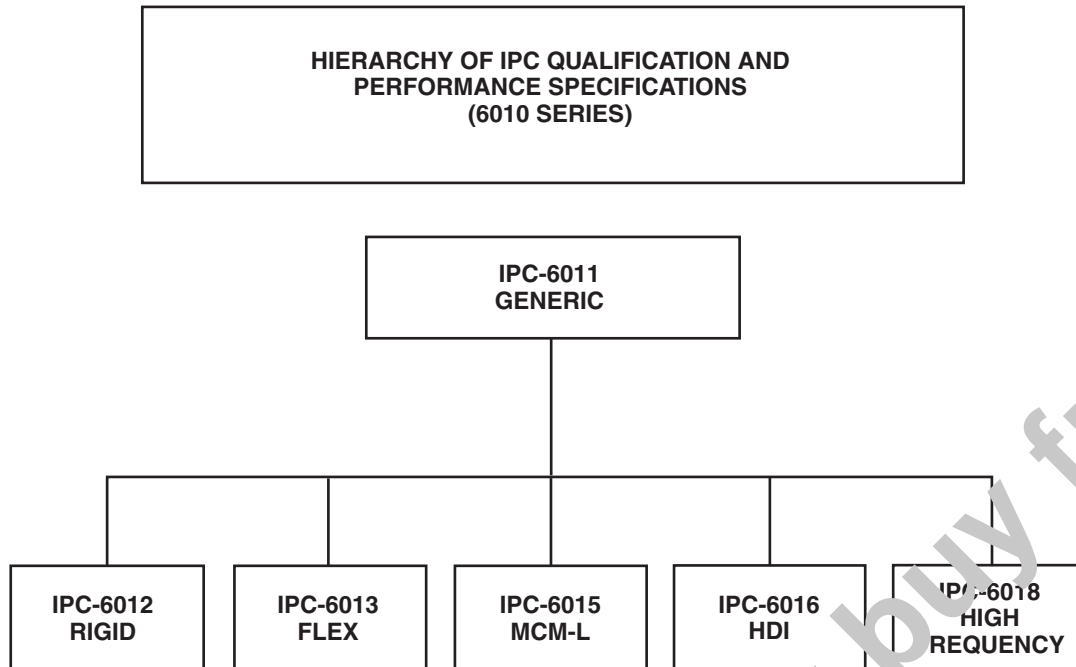
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Contact:

IPC
3000 Lakeside Drive, Suite 309S
Bannockburn, Illinois
60015-1249
Tel 847 615.7100
Fax 847 615.7105



FOREWORD

This specification is intended to provide information on the detailed performance criteria of rigid printed boards. It supersedes IPC-6012B and was developed as a revision to those documents. The information contained herein is also intended to supplement the generic requirements identified in IPC-6011. When used together, these documents should lead both manufacturer and customer to consistent terms of acceptability.

IPC's documentation strategy is to provide distinct documents that focus on specific aspects of electronic packaging issues. In this regard, document sets are used to provide the total information related to a particular electronic packaging topic. A document set is identified by a four digit number that ends in zero (0) (i.e., IPC-6010).

Included in the set is the generic information, which is contained in the first document of the set. The generic specification is supplemented by one or multiple performance documents, each of which provide a specific focus on one aspect of the topic or the technology selected.

Failure to have all information available prior to building a board may result in a conflict in terms of acceptability.

As technology changes, a performance specification will be updated, or new focus specifications will be added to the document set. The IPC invites input on the effectiveness of the documentation and encourages user response through completion of "Suggestions for Improvement" forms located at the end of each document.

Acknowledgment

Any document involving a complex technology draws material from a vast number of sources. While the principal members of the Rigid Printed Board Performance Specifications Task Group (D-33a) of the Rigid Printed Board Committee (D-30) are shown below, it is not possible to include all of those who assisted in the evolution of this standard. To each of them, the members of the IPC extend their gratitude.

Rigid Printed Board Committee	Rigid Printed Board Performance Specifications Task Group	Technical Liaisons of the IPC Board of Directors
Chair Vicka White Honeywell Inc. Air Transport Systems	Chair Mark Buechner BAE Systems	Peter Bigelow IMI Inc.
Vice-Chair Debora Obitz Trace Laboratories - East	Vice-Chair Randy R. Reed Viasystems Group, Inc.	Sammy Yi Flextronics International
Rigid Printed Board Performance Specifications Task Group		
Diane Andercyk, Trace Laboratories - East	Patricia S. Dupuis, Raytheon Company	Michael G. Luke, Raytheon Company
Lance Auer, Raytheon Missile Systems	Theodore Edwards, Dynaco Corp.	Clifford Maddox, Boeing Company
Robert F. Bagsby, Rockwell Collins	Alan Exley, Raytheon Company	Brian Madsen, Continental AG
Mary Bellon, Boeing Satellite Development Center	Gary Ferrari, FTG Circuits	Chris Mahanna, Robisan Laboratory Inc.
Wendi Boger, DDi Corp.	Lionel Fullwood, WKK Distribution Ltd.	Kenneth Manning, Raytheon Company
Gerald Leslie Bogert, Bechtel Plant Machinery, Inc.	Mahendra Gandhi, Northrop Grumman Aerospace Systems	Rene Martinez, Northrop Grumman Aerospace Systems
Scott Bowles, Hallmark Circuits Inc.	Tom Gardenour, Amphenol Printed Circuits Inc.	Matthew McQueen, NSWC Crane
Elaine Brown, Lockheed Martin Systems Integration	Thomas Gadecki, Gemini Sciences Tyngsboro, Unicircuit Inc.	Peter Menuetz, L-3 Communications - Cincinnati Electronics
Jennifer Burlingame, Cisco Systems Inc.	Harv Green, Lockheed Martin Space Systems Company	Renee J. Michalkiewicz, Trace Laboratories - East
Fritz Byle, Astronautics Corp. of America	Michael Green, Lockheed Martin Space Systems Company	Roger Miedico, Raytheon Company
Matthew Byrne, BAE Systems Platform Solutions	Philip Henault, Raytheon Company	Michael Miller, NSWC Crane
Byron Case, L-3 Communications	Michael Hill, Colonial Circuits Inc.	James Monarchio, TTM Technologies, Inc.
Laya Chen, Microtek (Changzhou) Product Services Co., Ltd.	Eddie Huddleston, Elbit Systems of America	Bob Neves, Microtek Laboratories
Pei-Liang Chen, Shanghai Printronics Electronics Co., Ltd.	Bryan James, Rockwell Collins	Steven M. Nolan, Lockheed Martin Maritime Systems & Sensors
Denise Cavalier, Amphenol Printed Circuits, Inc.	Todd Jarman, L-3 Communications	Debora Obitz, Trace Laboratories - East
Christine Coapman, Delphi Electronics and Safety	Candee Kaminski, Honeywell Inc. Air Transport Systems	William Ortloff, Raytheon Company
William C. Dieffenbacher, BAE Systems Platform Solutions	Thomas E. Kemp, Rockwell Collins	Michael Paddack, Boeing Company
C. Don Dupriest, Lockheed Martin Missiles and Fire Control	Jason Koch, Robisan Laboratory Inc.	J. Lee Parker, JLP
	Nick Koop, Minco Products Inc.	Mel Parrish, STI Electronics
	Karin LaBerge, Microtek Laboratories	Marybeth Perrino, Endicott Interconnect Technologies Inc
	Jeff Lewis, Holaday Circuits Inc.	Stephen Pierce, SGP Ventures, Inc.

Paul Reid, PWB Interconnect
Solutions Inc.

Jose Rios, Endicott Interconnect
Technologies Inc

Karl Sauter, Oracle America, Inc.

Joseph Schmidt, Raytheon Missile
Systems

Russell Shepherd, Microtek
Laboratories

Lowell Sherman, Defense Supply
Center Columbus

James Stack, Endicott Interconnect
Technologies Inc

Gordon Sullivan, Huntsman
Advanced Technology Center

Kevin Therault, Lockheed Martin
Space Systems Company

Dung Q. Tiet, Lockheed Martin
Space Systems Company

Bradley Toone, L-3 Communications

Crystal E. Vanderpan, Underwriters
Laboratories Inc.

Sharon Ventress, U.S. Army Aviation
& Missile Command

Clark Webster, ALL Flex LLC

Vicka White, Honeywell Inc. Air
Transport Systems

Dewey Whittaker, Honeywell Inc. Air
Transport Systems

James Wilson, Endicott Interconnect
Technologies Inc

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Qualification and Performance Specification for Rigid Printed Boards

1 SCOPE

1.1 Statement of Scope This specification establishes and defines the qualification and performance requirements for the fabrication of rigid printed boards.

1.2 Purpose The purpose of this specification is to provide requirements for qualification and performance of rigid printed boards based on the following constructions and/or technologies:

- Single-sided, double-sided printed boards with or without plated-through holes (PTHs).
- Multilayer printed boards with PTHs with or without buried/blind vias.
- Multilayer printed boards containing build up High Density Interconnect (HDI) layers conforming to IPC-6016.
- Active embedded passive circuitry printed boards with distributive capacitive planes and/or capacitive or resistive components.
- Metal core printed boards with or without an external metal heat frame, which may be active or nonactive.

1.2.1 Supporting Documentation IPC-A-600, which contains figures, illustrations, and photographs that can aid in the visualization of externally and internally observable acceptable/nonconforming conditions, may be used in conjunction with this specification for a more complete understanding of the recommendation and requirements.

1.3 Performance Classification and Type

1.3.1 Classification This specification establishes acceptance criteria for the performance classification of rigid printed boards based on customer and/or end-use requirements. Printed boards are classified by one of three general Performance Classes as defined in IPC-6011.

1.3.1.1 Requirement Deviations Requirements deviating from these heritage classifications **shall** be as agreed between user and supplier (AABUS).

1.3.1.2 Space and Military Avionics Deviations Space and Military Avionics performance classification deviations are defined and listed in Appendix A of this specification. These are commonly referred to as Class 3/A.

1.3.2 Printed Board Type Printed boards without PTHs (Type 1) and with PTHs (Types 2-6) are classified as follows:

Type 1—Single-Sided Printed Board

Type 2—Double-Sided Printed Board

Type 3—Multilayer Printed Board without blind or buried vias

Type 4—Multilayer Printed Board with blind and/or buried vias

Type 5—Multilayer metal core Printed Board without blind or buried vias

Type 6—Multilayer metal core Printed Board with blind and/or buried vias

1.3.3 Selection for Procurement Performance class **shall** be specified in the procurement documentation.

The procurement documentation **shall** provide sufficient information to fabricate the printed board and ensure that the user receives the desired product. Information that should be included in the procurement documentation is to be in accordance with IPC-D-325.